



PATENT
Attorney Docket No. 98124x205487

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Wang et al.

Art Unit: 1765

Application No. 09/636,161

Examiner: Lynette T. Umez-Eronini

Filed: August 10, 2000

For: POLISHING SYSTEM AND METHOD
OF ITS USE

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RESPONSE TO OFFICE ACTION

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated September 23, 2002, please consider the following remarks.

REMARKS

The Pending Claims

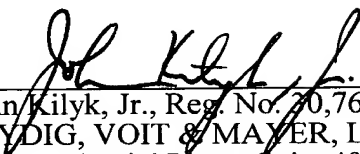
Claims 1, 3-6, 8, 9, 16-27, and 32-35 are currently pending. Claim 2 has been withdrawn from consideration by the Office as being directed to a non-elected species. Claims 1-6, 8, 9, 16-27, and 32-35 are directed to a system for polishing one or more layers of a multi-layer substrate comprising (i) a liquid carrier, (ii) at least one oxidizing agent, (iii) at least one polishing additive that increases the rate at which the system polishes at least one layer of the substrate, (iv) at least one passivation film-forming agent, and (v) a polishing pad and/or an abrasive. Reconsideration of the pending claims is respectfully requested.

Summary of the Office Action

Claims 1, 3-6, 8, 9, and 16-27 stand rejected under 35 U.S.C. § 103(a) as obvious over Sasaki (i.e., U.S. Patent 5,770,095) in combination with Kaufman (i.e., U.S. Patent 5,783,489). Applicants note that the Office Action does not list the status of claim 2. As stated above, claim 2 is directed to a non-elected species and should be listed as withdrawn from consideration.

In re Appln. of Wang et al.
Application No. 09/636,161

Respectfully submitted,



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Date: December 20, 2002

CERTIFICATE OF MAILING

I hereby certify that this RESPONSE TO OFFICE ACTION (along with any documents referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Date: December 20, 2002

